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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	359200
Number of Logic Elements/Cells	952000
Total RAM Bits	53248000
Number of I/O	840
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FBGA, FC (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxeabn3f45i4n

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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## **Recommended Operating Conditions**

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min <sup>(4)</sup>	Тур	Max <sup>(4)</sup>	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V <sub>CC</sub>	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) (3)	_	0.82	0.85	0.88	V
V <sub>CCPT</sub>	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V <sub>CCPD</sub> <sup>(1)</sup>	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
$V_{CCIO}$	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
$V_{CCPGM}$	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V <sub>CCA_FPLL</sub>	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V <sub>CCD_FPLL</sub>	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V <sub>CCBAT</sub> (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V <sub>I</sub>	DC input voltage	_	-0.5	_	3.6	V
V <sub>0</sub>	Output voltage	_	0	_	V <sub>CCIO</sub>	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T <sub>J</sub>	Operating junction temperature	Industrial	-40	_	100	°C

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Table 8 shows the transceiver power supply voltage requirements for various conditions.

**Table 8. Transceiver Power Supply Voltage Requirements** 

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB (2)	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:					
■ Data rate > 10.3 Gbps.	All	1.05			
■ DFE is used.					
If ANY of the following conditions are true <sup>(1)</sup> :			3.0		
ATX PLL is used.					
■ Data rate > 6.5Gbps.	All	1.0			
■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.				1.5	V
If ALL of the following	C1, C2, I2, and I3YY	0.90	2.5		
conditions are true:  ATX PLL is not used.					
■ Data rate ≤ 6.5Gbps.	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		
DFE, AEQ, and EyeQ are not used.					

### Notes to Table 8:

- (1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.
- (2) If the VCCR\_GXB and VCCT\_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR\_GXB and VCCT\_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

### **DC Characteristics**

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

### **Supply Current**

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

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Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,I4	Unit
50-Ω R <sub>S</sub>	Internal series termination with calibration (50- $\Omega$ setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
$34\text{-}\Omega$ and $40\text{-}\Omega$ $R_S$	Internal series termination with calibration (34- $\Omega$ and 40- $\Omega$ setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
$48$ - $\Omega$ , $60$ - $\Omega$ , $80$ - $\Omega$ , and $240$ - $\Omega$ R <sub>S</sub>	Internal series termination with calibration (48- $\Omega$ , 60- $\Omega$ , 80- $\Omega$ , and 240- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2 V	±15	±15	±15	±15	%
50-Ω R <sub>T</sub>	Internal parallel termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} 20\text{-}\Omega,30\text{-}\Omega,\\ 40\text{-}\Omega,60\text{-}\Omega,\\ \text{and}\\ 120\text{-}\OmegaR_T \end{array}$	Internal parallel termination with calibration (20- $\Omega$ , 30- $\Omega$ , 40- $\Omega$ , 60- $\Omega$ , and 120- $\Omega$ setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60- $\Omega$ and 120- $\Omega$ R <sub>T</sub>	Internal parallel termination with calibration (60- $\Omega$ and 120- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} \textbf{25-}\Omega \\ \textbf{R}_{S\_left\_shift} \end{array}$	Internal left shift series termination with calibration (25- $\Omega$ R <sub>S_left_shift</sub> setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

### Note to Table 11:

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

			Resistance Tolerance					
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit	
25-Ω R, 50-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CCIO</sub> = 3.0 and 2.5 V	±30	±30	±40	±40	%	
25-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CCIO</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%	
25-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%	

<sup>(1)</sup> OCT calibration accuracy is valid at the time of calibration only.

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## **Switching Characteristics**

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

## **Transceiver Performance Specifications**

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 1 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trar	sceive Grade	r Speed 2	Tran	sceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V	PCML,	1.4-V PCM	L, 1.5-V		2.5-V PCM HCSL	IL, Diffe	rential	LVPECL, L\	DS, and
Sidiludius	RX reference clock pin		1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS								
Input Reference Clock Frequency (CMU PLL) (8)	_	40	—	710	40		710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(8)</sup>	_	100		710	100		710	100	_	710	MHz
Rise time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	_	400	_		400	_	_	400	ne
Fall time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	—	400	_	_	400	_	_	400	ps
Duty cycle	_	45	_	55	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	_	33	30		33	30	_	33	kHz

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Transceiver Speed Grade 2			Trai	sceive Grade	r Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	_	dB
	DC Gain Setting = 1		2	_	_	2		_	2	_	dB
Programmable DC gain	DC Gain Setting = 2		4	_		4	_	_	4	_	dB
DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB	
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	_	dB
Transmitter											
Supported I/O Standards	_		1.4-V and 1.5-V PCML								
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
	85- $\Omega$ setting		85 ± 20%	_	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-	100-Ω setting		100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150-Ω setting		150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V <sub>OCM</sub> (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V <sub>OCM</sub> (DC coupled)	_		650	_	_	650	_	_	650	_	mV
Rise time (7)	20% to 80%	30	_	160	30	_	160	30	_	160	ps
Fall time <sup>(7)</sup>	80% to 20%	30	_	160	30	_	160	30		160	ps
Intra-differential pair skew	Tx V <sub>CM</sub> = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	_	_	120	_	_	120	_	_	120	ps

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Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Made (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode <sup>(2)</sup>	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO	FIFO 3	C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
		I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
		C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
		C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

### Notes to Table 25:

<sup>(1)</sup> The maximum data rate is in Gbps.

<sup>(2)</sup> The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

<sup>(3)</sup> The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

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Table 27 shows the  $\ensuremath{V_{OD}}$  settings for the GX channel.

Table 27. Typical V $_{\text{OD}}$  Setting for GX Channel, TX Termination = 100  $\Omega$   $^{(2)}$ 

Symbol	V <sub>OD</sub> Setting	V <sub>op</sub> Value (mV)	V <sub>op</sub> Setting	V <sub>op</sub> Value (mV)
	0 (1)	0	32	640
	1 (1)	20	33	660
	2 (1)	40	34	680
	3 (1)	60	35	700
	4 (1)	80	36	720
	5 <sup>(1)</sup>	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
<b>V</b> op differential peak to peak	15	300	47	940
typical <sup>(3)</sup>	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

### Note to Table 27:

- (1) If TX termination resistance =  $100\Omega$ , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

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Figure 2 shows the differential transmitter output waveform.

Figure 2. Differential Transmitter Output Waveform

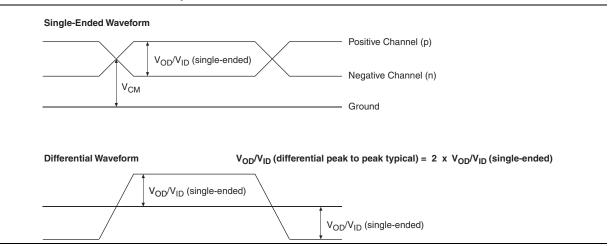


Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)



Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23.

Table 28 lists the Stratix V GT transceiver specifications.

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5)  $^{(1)}$ 

Symbol/	Conditions		Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Differential on-chip	GT channels	_	100	_		100	<u> </u>	Ω
termination resistors	GX channels			•	(8)		<u>'</u>	
\/	GT channels	_	500	_	_	500	_	mV
V <sub>OCM</sub> (AC coupled)	GX channels			•	(8)		<u>'</u>	
Diag/Fall time	GT channels	_	15	_	_	15	_	ps
Rise/Fall time	GX channels		<u>I</u>		(8)			
Intra-differential pair skew	GX channels				(8)			
Intra-transceiver block transmitter channel-to- channel skew	GX channels		(8)					
Inter-transceiver block transmitter channel-to- channel skew	GX channels		(8)					
CMU PLL								
Supported Data Range	_	600	_	12500	600	_	8500	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (14)	_	_	_	10	_	_	10	μs
ATX PLL								
	VCO post- divider L=2	8000	_	12500	8000	_	8500	Mbps
	L=4	4000	_	6600	4000	_	6600	Mbps
Supported Data Rate	L=8	2000	_	3300	2000	_	3300	Mbps
Range for GX Channels	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	_	14025	9800	_	12890	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (14)	_	_	_	10	_	_	10	μs
fPLL			•					
Supported Data Range	_	600	_	3250/ 3.125 <sup>(23)</sup>	600	_	3250/ 3.125 <sup>(23)</sup>	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	_	1	_	_	μs

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- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

## **Core Performance Specifications**

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

### **Clock Tree Specifications**

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

		Performance			
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	d C4, 14		
Global and Regional Clock	717	650	580	MHz	
Periphery Clock	550	500	500	MHz	

### Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

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## **PLL Specifications**

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range ( $-40^{\circ}$  to  $100^{\circ}$ C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f <sub>IN</sub>	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 <sup>(1)</sup>	MHz
INPFD	Input frequency to the PFD	5	_	325	MHz
FINPFD	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f <sub>vco</sub> <sup>(9)</sup>	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	_	1300	MHz
EINDUTY	Input clock or external feedback clock input duty cycle	40	_	60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	_	_	717 (2)	MHz
Гоит	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f <sub>OUT_EXT</sub>	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 (2)	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 <sup>(2)</sup>	MHz
t <sub>оитриту</sub>	Duty cycle for a dedicated external clock output (when set to <b>50%</b> )	45	50	55	%
FCOMP	External feedback clock compensation time	_		10	ns
DYCONFIGCLK	Dynamic Configuration Clock used for mgmt_clk and scanclk	_	_	100	MHz
Lock	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
DLOCK	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3		MHz
: CLBW	PLL closed-loop medium bandwidth		1.5		MHz
	PLL closed-loop high bandwidth (7)	_	4	_	MHz
PLL_PSERR	Accuracy of PLL phase shift		_	±50	ps
ARESET	Minimum pulse width on the areset signal	10	_	_	ns

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Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
<b>→</b> (3) (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> ≥ 100 MHz)	_	_	0.15	UI (p-p)
t <sub>INCCJ</sub> (3), (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> < 100 MHz)	-750		+750	ps (p-p)
+ (5)	Period Jitter for dedicated clock output ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175 <sup>(1)</sup>	ps (p-p)
t <sub>OUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5 <sup>(1)</sup>	mUI (p-p)
t (5)	Period Jitter for dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
+ (5)	Cycle-to-Cycle Jitter for a dedicated clock output $(f_{OUT} \ge 100 \text{ MHz})$	_	_	175	ps (p-p)
t <sub>outccj_dc</sub> (5)	Cycle-to-Cycle Jitter for a dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
+ (5)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTCCJ_DC</sub> <sup>(5)</sup>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)+	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
t <sub>OUTPJ_IO</sub> (5),	Period Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600	ps (p-p)
(8)	Period Jitter for a clock output on a regular I/O (f <sub>OUT</sub> < 100 MHz)	_	_	60	mUI (p-p)
t <sub>FOUTPJ 10</sub> (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>outccj_10</sub> (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>FOUTCCJ_IO</sub>	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600 (10)	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}}$ < 100 MHz)	_	_	60	mUI (p-p)
t <sub>CASC_OUTPJ_DC</sub> (5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175	ps (p-p)
	Period Jitter for a dedicated clock output in cascaded PLLs (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
f <sub>DRIFT</sub>	Frequency drift after PFDENA is disabled for a duration of 100 $\mu s$	_	_	±10	%
dK <sub>BIT</sub>	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k <sub>VALUE</sub>	Numerator of Fraction	128	8388608	2147483648	_

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Cumbal	Conditions		C1		C2, C2L, I2, I2L			., I3YY	C4,I4			IIi.		
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4  LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
- f <sub>HSDR</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f <sub>HSDR</sub> (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t <sub>x Jitter</sub> - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t <sub>x Jitter</sub> - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

			C1		C2,	C2L, I	2, I2L	C3, I3, I3L, I3YY			C4,I4			
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t <sub>DUTY</sub>	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t <sub>RISE</sub> & t <sub>FALL</sub>	Emulated Differential I/O Standards with three external output resistor networks	_		250	_	_	250	_		250	_		300	ps
	True Differential I/O Standards	_	_	150	_		150		_	150			150	ps
TCCS	Emulated Differential I/O Standards	_	_	300	_	_	300	_		300	_	_	300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150	_	1434	150	_	1434	150	_	1250	150		1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4  LVDS RX with DPA (12), (14), (15), (16)	150	_	1600	150	_	1600	150	_	1600	150	_	1250	Mbps
- f <sub>HSDRDPA</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps

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Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 2 of 2)

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

### Notes to Table 40:

- (1) The typical value equals the average of the minimum and maximum values.
- (2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t<sub>DQS\_PSERR</sub>) for Stratix V Devices (1)

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

#### Notes to Table 41:

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 1 of 2) (2), (3)

Clock Network	Parameter	Symbol	C1 C2, C2L, I2,		, I2, I2L	C3, I3, I3L, I3YY		C4,I4		Unit	
NEIWUIK			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t <sub>JIT(per)</sub>	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	t <sub>JIT(cc)</sub>	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t <sub>JIT(per)</sub>	-75	75	<del>-</del> 75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	t <sub>JIT(cc)</sub>	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	t <sub>JIT(duty)</sub>	<del>-</del> 75	75	-75	75	-90	90	-90	90	ps

<sup>(1)</sup> This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a −2 speed grade is ±78 ps or ±39 ps.

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Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Mombou		Active Serial (1)	1	Fast Passive Parallel (2)			
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	D3	4	100	0.344	32	100	0.043	
	D4	4	100	0.534	32	100	0.067	
GS		4	100	0.344	32	100	0.043	
นอ	D5	4	100	0.534	32	100	0.067	
	D6	4	100	0.741	32	100	0.093	
	D8	4	100	0.741	32	100	0.093	
E	E9	4	100	0.857	32	100	0.107	
_	EB	4	100	0.857	32	100	0.107	

### Notes to Table 48:

## **Fast Passive Parallel Configuration Timing**

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

### DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
IFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
FFF XIO	Enabled	Disabled	4
	Enabled	Enabled	4

<sup>(1)</sup> DCLK frequency of 100 MHz using external CLKUSR.

<sup>(2)</sup> Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1  $^{(1)}$ 

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nconfig low to conf_done low	_	600	ns
t <sub>CF2ST0</sub>	nconfig low to nstatus low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(2)</sup>	μS
t <sub>CF2ST1</sub>	nconfig high to nstatus high	_	1,506 <sup>(2)</sup>	μS
t <sub>CF2CK</sub> (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t <sub>ST2CK</sub> (5)	nstatus high to first rising edge of DCLK	2	_	μS
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	N-1/f <sub>DCLK</sub> <sup>(5)</sup>	_	S
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f <sub>MAX</sub>	DCLK frequency (FPP ×32)	_	100	MHz
t <sub>R</sub>	Input rise time	_	40	ns
t <sub>F</sub>	Input fall time	_	40	ns
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum  DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	t <sub>CD2CU</sub> + (8576 × CLKUSR period) <sup>(4)</sup>	_	_

### Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.
- (6) If nstatus is monitored, follow the  $t_{status}$  specification. If nstatus is not monitored, follow the  $t_{cfack}$  specification.

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Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	<del>-</del>
1		
J	JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus).  JTAG Timing Specifications:  TMS  TDI  TCK  TJPSU  TJ
K L M N	_	
P	PLL Specifications	Diagram of PLL Specifications (1)  CLKOUT Pins  Four Core Clock  Reconfigurable in User Mode  External Feedback  Note:  (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.
Q	_	<del>-</del>
R	R <sub>L</sub>	Receiver differential input discrete resistor (external to the Stratix V device).
	_ <u>-</u>	1

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### Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions
	V <sub>CM(DC)</sub>	DC common mode input voltage.
	V <sub>ICM</sub>	Input common mode voltage—The common mode of the differential signal at the receiver.
	V <sub>ID</sub>	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V <sub>DIF(AC)</sub>	AC differential input voltage—Minimum AC input differential voltage required for switching.
	V <sub>DIF(DC)</sub>	DC differential input voltage— Minimum DC input differential voltage required for switching.
	V <sub>IH</sub>	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	V <sub>IH(AC)</sub>	High-level AC input voltage
	V <sub>IH(DC)</sub>	High-level DC input voltage
V	<b>V</b> <sub>IL</sub>	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	V <sub>IL(AC)</sub>	Low-level AC input voltage
	V <sub>IL(DC)</sub>	Low-level DC input voltage
	V <sub>OCM</sub>	Output common mode voltage—The common mode of the differential signal at the transmitter.
	<b>V</b> <sub>OD</sub>	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	V <sub>SWING</sub>	Differential input voltage
	V <sub>X</sub>	Input differential cross point voltage
	<b>V</b> <sub>OX</sub>	Output differential cross point voltage
W	W	High-speed I/O block—clock boost factor
Χ		
Υ		_
Z		

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